

REV.	ECN.	NO.	APPD.
A	BC-07-7068506	C.C. Huang	

- NOTES:
- ELECTRICAL CHARACTERISTICS:
 - 1-1 CURRENT RATING: 1.1 A MIN., 30°C RISE ABOVE AMBIENT.
 - 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
 - 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
 - MECHANICAL CHARACTERISTICS:
 - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
 - 2-4 CONTACT RETENTION FORCE: 4.9 N MIN.
 - ENVIRONMENTAL CHARACTERISTICS:
 - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .
 - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCTION DETAILS & AVAILABILITY
 - RECOMMENDED PROCESS CONDITION: WAVE SOLDER , 260°C , 3~5 S.

PROD. NO.: 2EG 0 ** * * - D2DB- **

FIELD PRODUCT SERIES: 2EG= PCI EXPRESS

TERMINAL TYPE: 0= VERTICAL TYPE

NO. OF POS. 32= 64 POSITIONS
49= 98 POSITIONS

PLATING TYPE: DN= TIN/LEAD

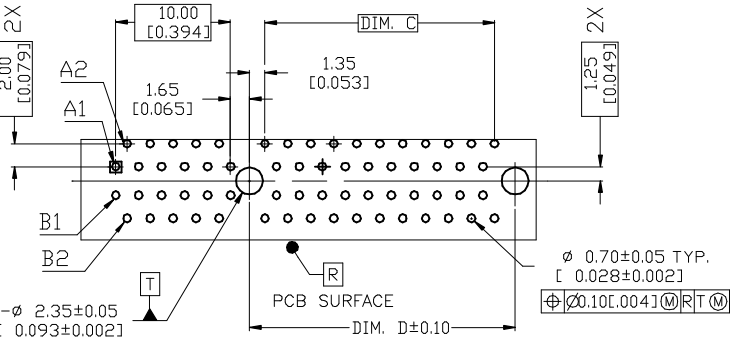
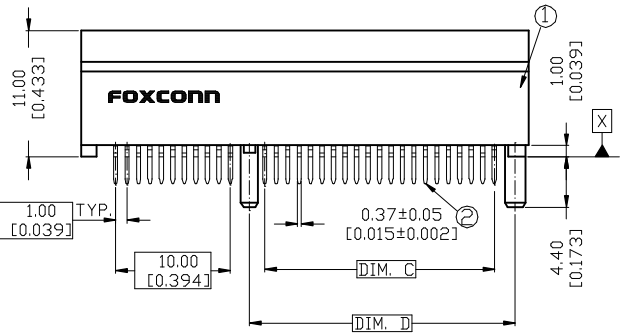
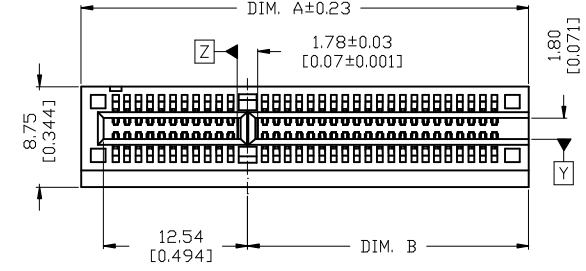
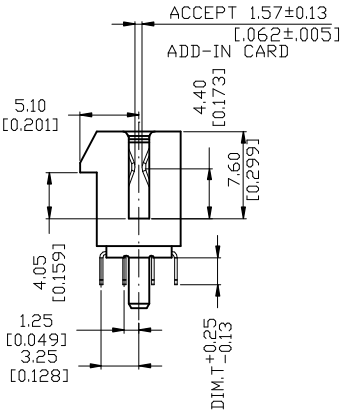
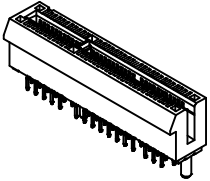
EXTENSION CODE

CONTACT AREA GOLD PLATING:
1= GOLD FLASH
7= 15u" GOLD
3= 30u" GOLD

TAIL LENGTH:
1= 2.30mm
2= 3.10mm

2EG0**2*-D2DB-**-**	3.10[1.22]
2EG0**1*-D2DB-**-**	2.30[0.90]
PRODUCT NUMBER	DIM. T

2	CONTACT	COPPER ALLOY	50u" MIN. NICKEL PLATING OVERALL UNDERPLATED. 100u" MIN. TIN PLATING OVER NICKEL AT TAIL , GOLD PLATING ON CONTACT AREA.
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK
ITEM	DESCRIPTION	MATERIAL	TREATMENT
X.±	X*±	UNITS mm INCH	NAME<INTENDED USE> 4X & 8X, T/H WITH OPEN END
.X±	.X*±	MAT'L	PART NO.<INTENDED USE> 2EG0****-D2DB-**-**
.XX±	.XX*±	N/A	APPD: C.C. Huang 10/20'07
.XXX±	.XXX*±	FINISH	CHKD: Tin-Suen Liu 10/20'07
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		N/A	DWG. NO.: 303-0000-1569
			SCALE SHEET REV. N/A 1/2 A

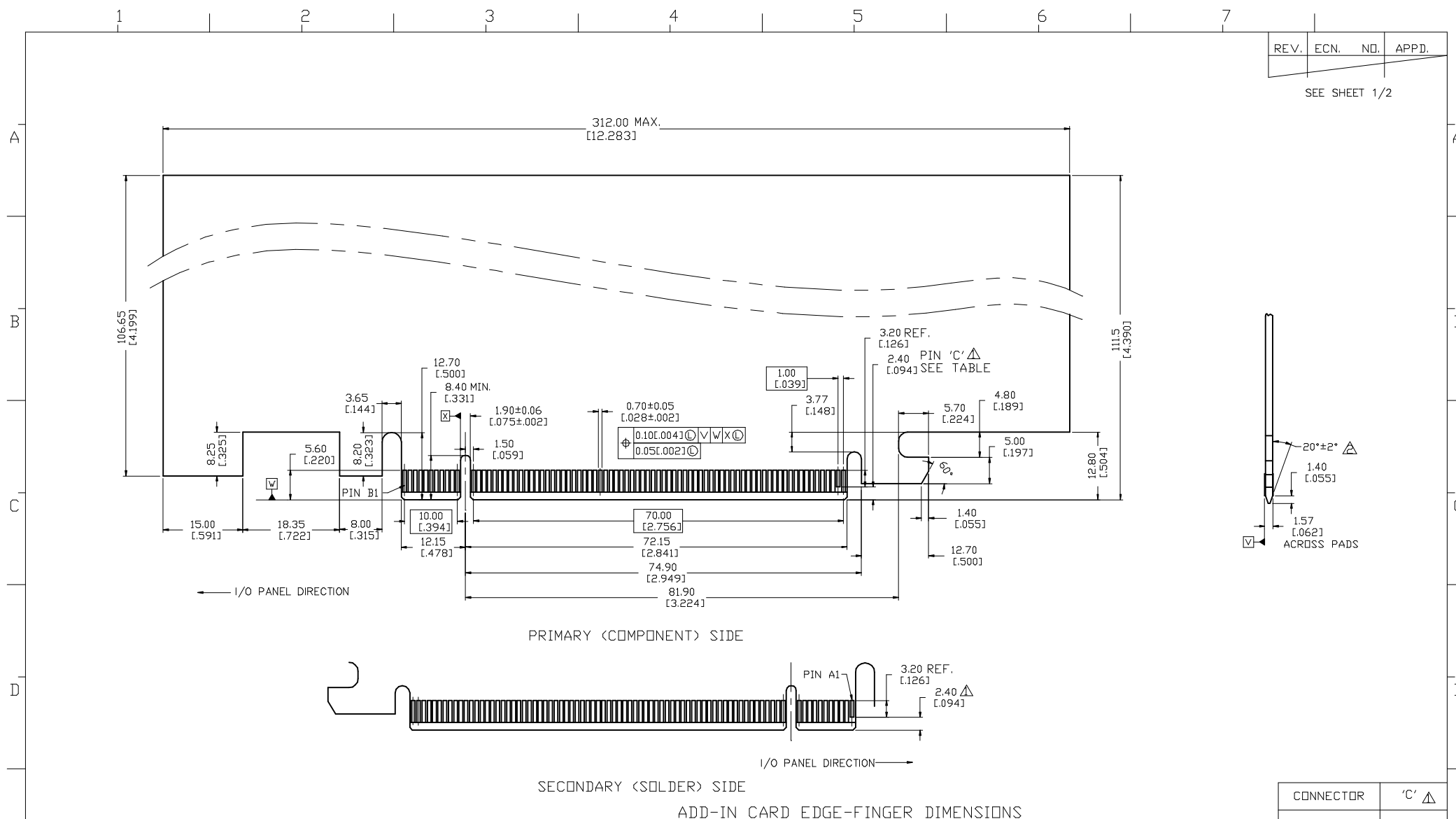


RECOMMENDED PCB LAYOUT

2EG049**-D2DB-**-**	56.00[2.205]	41.50[1.634]	37.00[1.457]	40.15[1.581]
2EG032**-D2DB-**-**	39.00[1.535]	24.50[0.965]	20.00[0.787]	23.15[0.911]
PRODUCT NUMBER	DIM. A	DIM. B	DIM. C	DIM. D

REV.	ECN.	NO.	APPD.

SEE SHEET 1/2



NOTES:

- △ NO TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'C'.
- △ CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

X. ±		X.° ±	UNITS	mm	NAME (INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.
.X ±		.X° ±	MAT'L	N/A	4X & 8X, T/H WITH OPEN END	
.XX ±		.XX° ±			PART NO. (INTENDED USE)	TITLE:
.XXX ±		.XXX° ±	FINISH	N/A	2EG0***-D2DB-**	CUSTOMER DRAWING
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				Q'TY	N/A	303-0000-1569
				CHKD:	Tin-Suen Liu 10/20'07	
				DR:	W.J Tang 10/20'07	
						SCALE SHEET REV.
						N/A 2/2 A